



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IRF150P221	<b>Issued</b>	26. June 2021
<b>MA#</b>	MA005571266		
<b>Package</b>	PG-TO247-3-901	<b>Weight*</b>	5731.46 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.046	0.12	0.12	1229	1229
leadframe	inorganic material	phosphorus	7723-14-0	1.131	0.02		197	
	non noble metal	iron	7439-89-6	3.771	0.07		658	
	non noble metal	copper	7440-50-8	3,765.728	65.70	65.79	657028	657883
wire	non noble metal	aluminium	7429-90-5	17.083	0.30	0.30	2981	2981
encapsulation	organic material	carbon black	1333-86-4	9.583	0.17		1672	
	plastics	epoxy resin	-	383.329	6.69		66881	
	inorganic material	silicondioxide	60676-86-0	1,523.732	26.59	33.45	265854	334407
leadfinish	non noble metal	tin	7440-31-5	13.948	0.24	0.24	2434	2434
solder	non noble metal	tin	7440-31-5	0.122			21	
	noble metal	silver	7440-22-4	0.153			27	
	non noble metal	lead	7439-92-1	5.834	0.10	0.10	1018	1066
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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